

Exhibit C

# **Semiconductor Terminology**

## ***Graphic Glossary of Terms***

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By Peter Van Zant**

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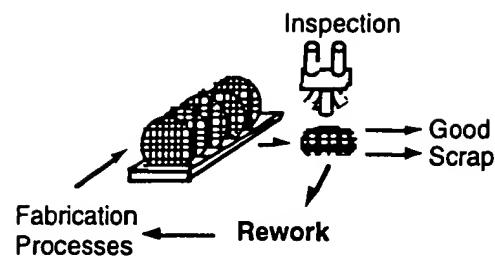
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## REWORK:

Out-of-specification wafers that are sent through a process again.



## REWORK RATE:

The percentage of wafers requiring rework.

**Rework Rate =**

$$\frac{\# \text{ Reworked Wafers}}{\# \text{ Wafers started in process step}} \times 100 \%$$

## RF:

See "Radio Frequency".

## RF HEATING:

See "Radio Frequency Heating".

## RIE:

See "Reactive Ion Etch".

## RINSE:

The removal of cleaning solutions, etchants or developers etc. from the wafer using water. This process stops the processes by removing the active chemical from the surface. There are several different methods of rinsing: overflow rinsing, dump rinsing, and spin/rinse drying.

